

the fluoropolymer matrix, wherein the remaining layer of resin comprises material of the resin that has not impregnated the fluoropolymer matrix; and

laminating the resin-impregnated fluoropolymer matrix to a conductor, wherein the conductor and the remaining layer of resin are disposed on opposite sides of the resin-impregnated fluoropolymer matrix following the laminating step.

24. (Original) The method of claim 23, wherein the fluoropolymer matrix is nonfibrillated polytetrafluoroethylene.

25. (Original) The method of claim 23, wherein the particles are inorganic particles.

26-31. (Canceled)

32. (Original) The method of claim 23, wherein the device is a printed circuit board.

33. (Previously presented) The method of claim 23, wherein the device is a chip carrier.

34. (Canceled)

35. (Previously presented) The method of claim 23, wherein the thermosetting resin includes solvent.

36. (Original) The method of claim 35, further comprising the step of heating the coated fluoropolymer matrix to remove the solvent from the thermosetting resin, prior to the laminating step.

37. (Previously presented) The method of claim 23, further comprising the step of subjecting the fluoropolymer matrix to a plasma process, prior to the coating step.

38-39. (Canceled)

40. (Previously presented) The method of claim 23, wherein the laminating step comprises applying heat and pressure.

41. (Currently amended) The method of claim 40, wherein the heat is applied at 120-250° C during the laminating step, and wherein the pressure is applied at 100-700 PSI during the laminating step.

42. (Canceled)

43. (Previously presented) The method of claim 23, wherein the fluoropolymer matrix is impregnated with the thermosetting resin, prior to the providing step.

44. (Canceled)

45. (Previously presented) The method of claim 35, further comprising the steps of:
coating the conductor with the thermosetting resin, prior to the laminating step; and
heating the coated conductor to remove the solvent from the thermosetting resin.

46-48. (Canceled)

49. (Original) The method of claim 23, wherein the thermosetting resin comprises inorganic particles, and wherein the inorganic particles of the thermosetting resin do not impregnate the fluoropolymer matrix during the processing step.

50. (Canceled)

51. (New) A method for forming a printed circuit board, comprising:
applying a first filled body on a first conductive layer, including coating a first thermosetting resin on at least one of a bottom surface of the first filled body and a top surface of the first conductive layer, said first filled body comprising a first fluoropolymer matrix having first particles therein;
layering a second conductive layer on a top surface of the first filled body; including coating a second thermosetting resin on at least one of a bottom surface of the second conductive layer and a top surface of the first filled body;
providing an article and positioning the article on the second conductive layer, said article comprising a second filled body having a second thermosetting resin coated thereon, said second

filled body comprising a second fluoropolymer matrix having second particles therein and material of said second thermosetting resin therein;

placing a third conductive layer on the article such that a bottom surface of the third conductive layer is on the article; and

laminating the first conductive layer, the first filled body, the second conductive layer, the article, and the third conductive layer to form the printed circuit board

52. (New) The method of claim 51, wherein providing the article comprises:

providing the second filled body;

coating the second thermosetting resin on the second filled body; and

forming the article by processing the second filled body with the second resin coated thereon such that material from the second resin impregnates the second fluoropolymer matrix, leaving a remaining layer of second resin on a surface of the second fluoropolymer matrix, wherein the remaining layer of second resin comprises material of the second resin that has not impregnated the second fluoropolymer matrix.

53. (New) The method of claim 51, further comprising prior to said laminating: coating a third thermosetting resin on a top surface of the third conductive layer.

54. (New) The method of claim 51, wherein coating the first thermosetting resin comprises coating the first thermosetting resin on the bottom surface of the first filled body, and wherein coating the second thermosetting resin comprises coating the second thermosetting resin on the

bottom surface of the second conductive layer.

55. (New) The method of claim 51, wherein coating the first thermosetting resin comprises coating the first thermosetting resin on the bottom surface of the first filled body, and wherein coating the second thermosetting resin comprises coating the second thermosetting resin on the top surface of the first filled body.

56. (New) The method of claim 51, wherein coating the first thermosetting resin comprises coating the first thermosetting resin on the top surface of the first conductive layer, and wherein coating the second thermosetting resin comprises coating the second thermosetting resin on the bottom surface of the second conductive layer.

57. (New) The method of claim 51, wherein coating the first thermosetting resin comprises coating the first thermosetting resin on the top surface of the first conductive layer, and wherein coating the second thermosetting resin comprises coating the second thermosetting resin on the top surface of the first filled body.